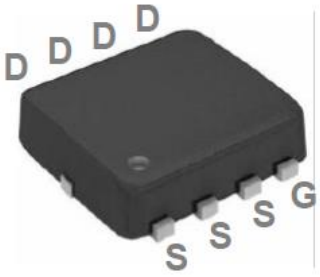
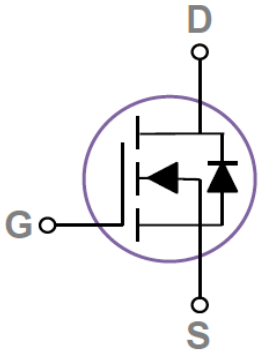
General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

DFN3x3 Pin Configuration





BVDSS	RDSON	ID
30V	8.5mΩ	48A

Features

◆30V,48A, RDS(ON) =8.5mΩ@VGS = 10V
◆Improved dv/dt capability
◆Fast switching
◆100% EAS Guaranteed
◆Green Device Available

Application

◆MB / VGA / Vcore
◆POL Applications
◆SMPS 2nd SR

Ordering Information

ECP3908Z XX X X

Package：
F：DFN3*3

G：Green Package

Taping：
R：Tape and Reel

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Drain Current – Continuous (T_C=25℃)	48	A
	Drain Current – Continuous (T_C=100℃)	30	A
I_{DM}	Drain Current – Pulsed[1]	192	A
EAS	Single Pulse Avalanche Energy[2]	45	mJ
IAS	Single Pulse Avalanche Current[2]	30	A
P_D	Power Dissipation (T_C=25℃)	35	W
	Power Dissipation – Derate above 25℃	0.28	W/℃
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	3.6	℃/W

Static State Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	30	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.04	---	V/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=30V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=24V , V_{GS}=0V , T_J=125℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
$R_{DS(ON)}$	Static Drain-Source On-Resistance[3]	V_{GS}=10V , I_D=16A	---	6.2	8.5	mΩ
		V_{GS}=4.5V , I_D=8A	---	9	13	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=VDS , I_D =250uA	1.2	1.6	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4	---	mV/℃
gfs	Forward Transconductance	V_{DS}=10V , I_D=8A	---	9.5	---	S

Dynamic Characteristics

Q_g	Total Gate Charge[3 , 4]	V_{DS}=15V , V_{GS}=4.5V , I_D=20A	---	7.5	12	nC
Q_{gs}	Gate-Source Charge[3 , 4]		---	1.3	2.6	
Q_{gd}	Gate-Drain Charge[3 , 4]		---	4.5	8	
$T_{d(on)}$	Turn-On Delay Time[3 , 4]	V_{DD}=15V , V_{GS}=10V , R_G=3.3 I_D=15A	---	4.8	9	ns
T_r	Rise Time[3 , 4]		---	12.5	24	
$T_{d(off)}$	Turn-Off Delay Time[3 , 4]		---	27.6	52	
T_f	Fall Time[3 , 4]		---	8.2	16	

C_{iss}	Input Capacitance	V_{DS}=25V , V_{GS}=0V , F=1MHz	---	680	1000	pF
C_{oss}	Output Capacitance		---	150	220	
C_{rss}	Reverse Transfer Capacitance		---	70	105	
Rg	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	2.7	5.4	Ω

Guaranteed Avalanche Energy

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	V_{DD}=25V, L=0.1mH, I_{AS}=15A	12	---	---	mJ

Drain-Source Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	48	A
I_{SM}	Pulsed Source Current[3]		---	---	192	A
V_{SD}	Diode Forward Voltage[3]	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V
t_{rr}	Reverse Recovery Time	V_{GS}=0V,I_S=1A , di/dt=100A/μs T_J=25℃	---	---	---	ns
Q_{rr}	Reverse Recovery Charge		---	---	---	nC

Note :

1.Repetitive Rating : Pulsed width limited by maximum junction temperature.

2.V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=30A.,RG=25Ω,Starting T_J=25℃.

3.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.

4.Essentially independent of operating temperature.

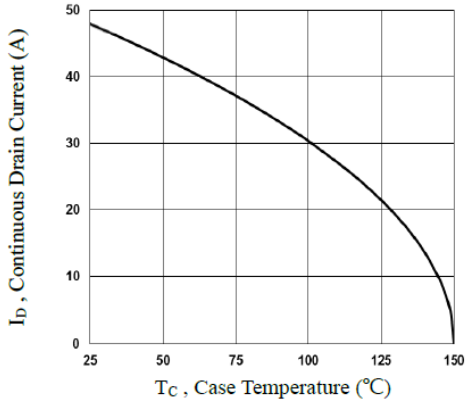


Fig.1 Continuous Drain Current vs. T_C

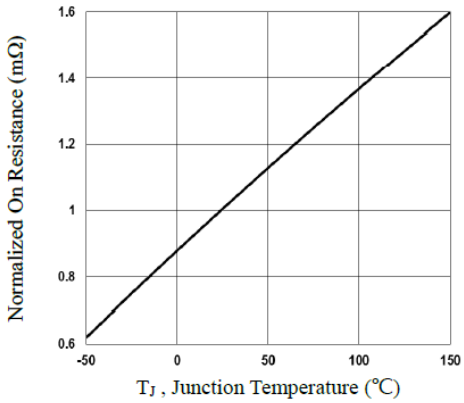


Fig.2 Normalized RDSON vs. T_J

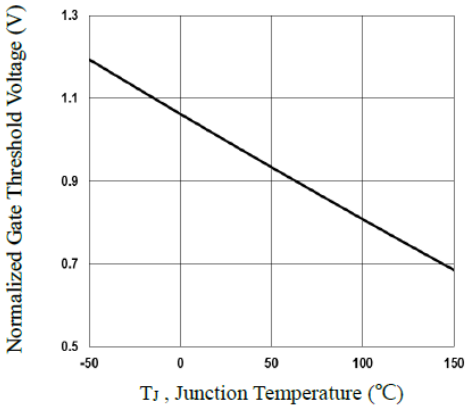


Fig.3 Normalized V_{th} vs. T_J

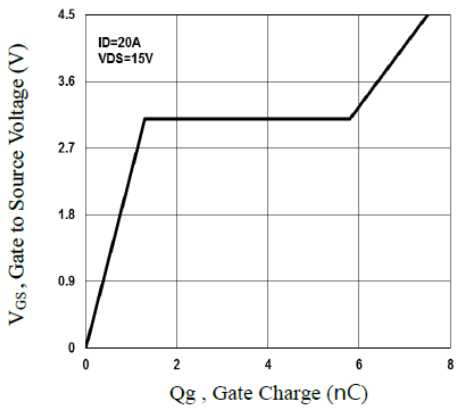


Fig.4 Gate Charge Waveform

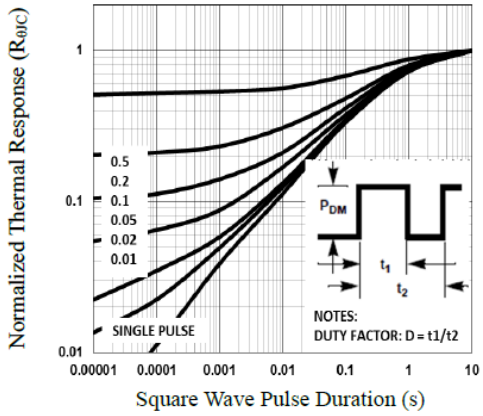


Fig.5 Normalized Transient Impedance

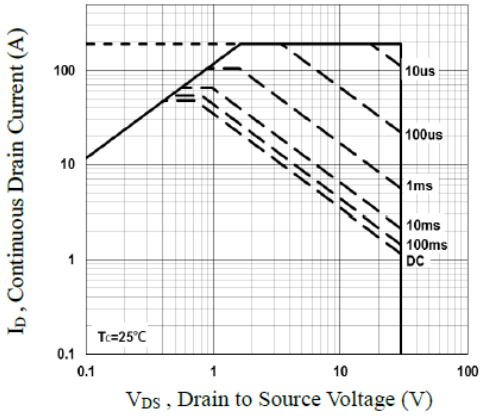


Fig.6 Maximum Safe Operation Area

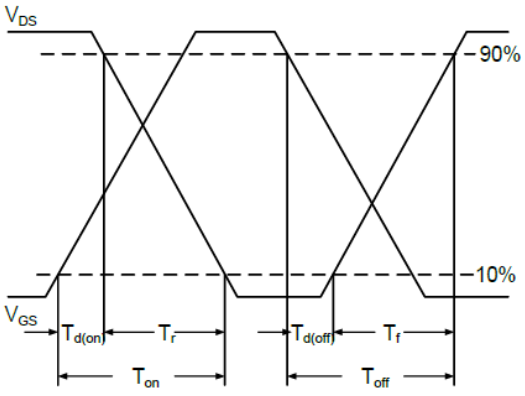


Fig.7 Switching Time Waveform

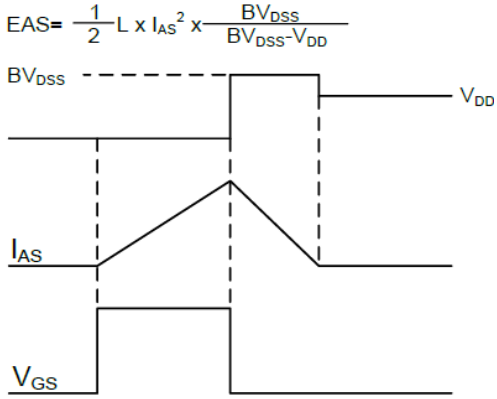
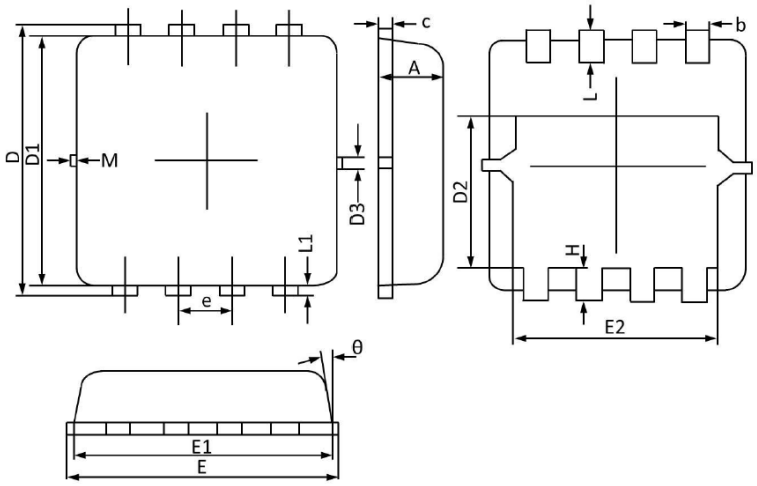


Fig.8 EAS Waveform

DFN3x3 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	